



Product Change Notification: DSNO-22ZCDA626

Date:

25-Jun-2026

Product Category:

Ethernet Bridges

Notification Subject:

CCB 8370 Final Notice: Qualification of MTAI as an additional assembly site for LAN7431/YXX, LAN7431-I/YXX, LAN7431T/YXX, LAN7431T-I/YXX, LAN7431T-V/YXX and LAN7431-V/YXX catalog part numbers (CPN) available in 72L VQFN (10x10x0.9mm) package.

Affected CPNs:

[DSNO-22ZCDA626_Affected_CPN_06252026.pdf](#)

[DSNO-22ZCDA626_Affected_CPN_06252026.csv](#)

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of MTAI as an additional assembly site for LAN7431/YXX, LAN7431-I/YXX, LAN7431T/YXX, LAN7431T-I/YXX, LAN7431T-V/YXX and LAN7431-V/YXX catalog part numbers (CPN) available in 72L VQFN (10x10x0.9mm) package.

Pre and Post Summary Changes:

	Pre Change	Post Change		Change (Yes/No)
Assembly Site	ASE Inc. (ASE)	ASE Inc. (ASE)	Microchip Technology Thailand (HQ) (MTAI)	Yes
Wire Material	CuPdAu	CuPdAu	CuPdAu	No

Die Attach Material	EN-4900F (PFAS-free)	EN-4900F (PFAS-free)	QMI519 (PFAS-free)	Yes
Molding Compound Material	G631H	G631H	G700LTD	Yes
Lead-Frame Material	C194	C194	A194	No
DAP Surface Prep	Ag	Ag	Ag Ring Plated	Yes
Lead-Frame Design	See Pre and Post Change Summary attachment for comparison.			

Note: *C194, A194 or CDA194 Lead frame material are the same, it is just a MCHP internal labelling difference.

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve on-time delivery performance by qualifying MTAI as an additional assembly site.

Change Implementation Status: In Progress

Estimated First Ship Date: 17 July 2026 (date code: 2629)

Note Below EFSD: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	June 2026				July 2026				
Work Week	23	24	25	26	27	28	29	30	31
Qual Report Availability				x					
Final PCN Issue Date				x					
Estimated Implementation Date							x		

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: June 25, 2026: Issued final notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

[PCN_DSNO-22ZCDA626_Pre and Post Change Summary.pdf](#)
[PCN_DSNO-22ZCDA626_Qual_Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN):

LAN7431/YXX

LAN7431-I/YXX

LAN7431T/YXX

LAN7431T-I/YXX

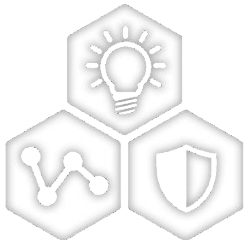
LAN7431T-V/YXX

LAN7431-V/YXX

CCB 8370
Pre and Post Change Summary
PCN #: DSNO-22ZCDA626

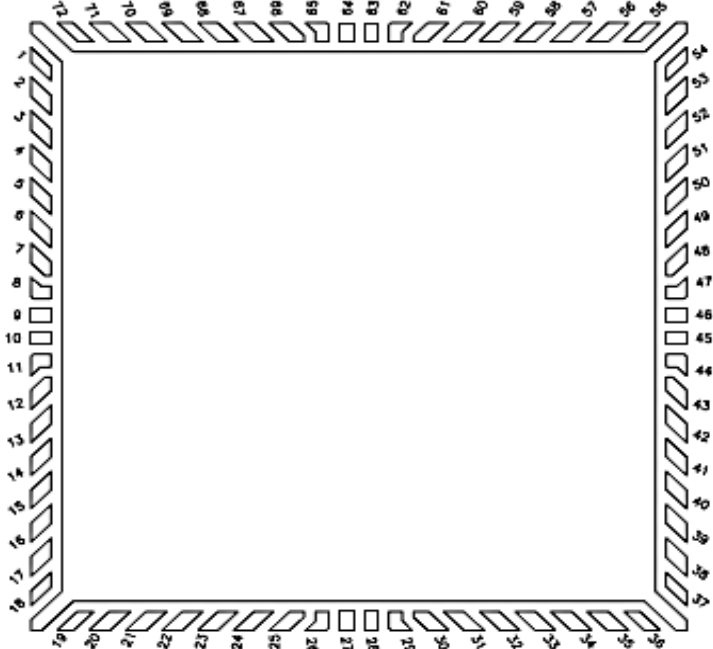
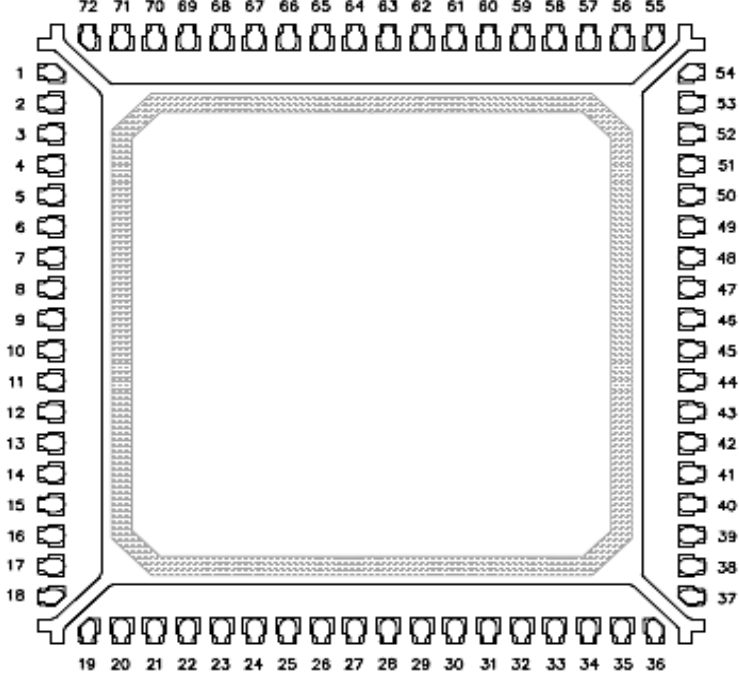


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Lead-Frame Comparison

ASE	MTAI								
ASE  Note: Not-to-scale <table border="1" data-bbox="211 1096 1174 1205"><tr><td>Lead-Frame Material</td><td>C194</td></tr><tr><td>DAP Surface Prep</td><td>Ag</td></tr></table>	Lead-Frame Material	C194	DAP Surface Prep	Ag	MTAI  Note: Not-to-scale <table border="1" data-bbox="1327 1096 2290 1205"><tr><td>Lead-Frame Material</td><td>A194</td></tr><tr><td>DAP Surface Prep</td><td>Ag Ring Plated</td></tr></table>	Lead-Frame Material	A194	DAP Surface Prep	Ag Ring Plated
Lead-Frame Material	C194								
DAP Surface Prep	Ag								
Lead-Frame Material	A194								
DAP Surface Prep	Ag Ring Plated								

Note: *C194, A194 or CDA194 Lead frame material are the same, it is just a MCHP internal labelling difference



QUALIFICATION REPORT SUMMARY

RELIABILITY LABORATORY

PCN #: DSNO-22ZCDA626

Date:
June 22, 2026

Qualification of QMI519 as a new die attach material for USX5007C/KD catalog part number (CPN) available in 100L VQFN (12X12X0.9mm) package assembled at MTAI assembly site. This is a Q006 Grade 3 Qualification.

Qualification of MTAI as an additional assembly site for LAN7431/YXX, LAN7431-I/YXX, LAN7431T/YXX, LAN7431T-I/YXX, LAN7431T-V/YXX and LAN7431-V/YXX catalog part numbers (CPN) available in 72L VQFN (10x10x0.9mm) package. This is a qualification by similarity (QBS).



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PACKAGE QUALIFICATION REPORT

Purpose

Qualification of QMI519 as a new die attach material for USX5007C/KD catalog part number (CPN) available in 100L VQFN (12X12X0.9mm) package assembled at MTAI assembly site. This is a Q006 Grade 3 Qualification. Qualification of MTAI as an additional assembly site for LAN7431/YXX, LAN7431-I/YXX, LAN7431T/YXX, LAN7431T-I/YXX, LAN7431T-V/YXX and LAN7431-V/YXX catalog part numbers (CPN) available in 72L VQFN (10x10x0.9mm) package. This is a qualification by similarity (QBS).

CN	E000246496
QUAL ID	R2401317 Rev. A
MP CODE	STB071KDXC50
Part No.	USX5007C/KD
Bonding No.	BD-002245 Rev. 01
CCB No.	6910 (Qual Date: March 4, 2025) and 8370
<u>Package</u>	
Type	100L VQFN
Package size	12 x 12 x 0.9mm
<u>Lead Frame</u>	
Paddle size	323x323 mils
Material	EFTEC64
Surface	Ag signal ring plated on DAP
Process	Etched
Lead Lock	No
Part Number	10110011
Treatment	Roughening
<u>Material</u>	
Epoxy	QMI519
Wire	CuPdAu wire
Mold Compound	G700LTD
Plating Composition	Matte Sn



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PACKAGE QUALIFICATION REPORT

Manufacturing Information

Assembly Lot No.	Wafer Lot No.	Date Code
MTAI252600940.000	TC14924313854.200	2439YD7
MTAI252601144.000	TC14924313854.200	2439YT8
MTAI252601148.000	TC14924313854.200	2439YTK

Result ☒ Pass ☐ Fail ☐ _____

100L VQFN (12x12x0.9mm) assembled by MTAI pass reliability test per QCI-39000.
This package was qualified the Moisture/Reflow Sensitivity Classification Level 3 at 260°C
reflow temperature per IPC/JEDEC J-STD-020E standard.

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS	Result	Remarks
Moisture/Reflow Sensitivity Classification Test (At MSL Level 3)	30°C/ 60%RH Moisture Soak 192 hrs. System: TABAI ESPEC Model PR-3SPH 3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243 (IPC/JEDEC J-STD-020E)	IPC/JEDEC J-STD-020E	135(0)	0/135	Pass	
Precondition Prior Perform Reliability Tests (At MSL Level 3)	Electrical Test: +25°C and 85°C System: LTX_D1X Bake 150°C, 24 hrs System: CHINEE 30°C/60%RH Moisture Soak 192 hrs. System: TABAI ESPEC Model PR-3SPH 3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243 Electrical Test: +25°C and 85°C System: LTX_D1X	JESD22-A113	693(0)	0/693 693 693 693 0/693	Pass Pass Pass Pass	Good Devices

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Temp Cycle	Stress Condition: -55°C to +125°C, 500 Cycles System : VOTSCH Electrical Test: +25°C and 85°C System: LTX_D1X Bond Strength: Wire Pull (>3.00 grams) Bond Shear (>8.00 grams)	JESD22-A104		231		Parts had been pre-conditioned at 260°C
			231(0)	0/231	Pass	
			45 (0)	0/45	Pass	Wire pull & bond shear after Temp Cycle
	Stress Condition: -55°C to +125°C, 1000 Cycles System: VOTSCH Electrical Test: +25°C and 85°C System: LTX_D1X Bond Strength: Wire Pull (>3.00 grams) Bond Shear (>8.00 grams)			231		
			231(0)	0/231	Pass	
			45 (0)	0/45		Wire pull & bond shear after Temp Cycle

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
HAST	Stress Condition: +110°C/85%RH, 264 hrs. Bias Volt: PS1:1.32 Volts, PS3: 3.63 Volts System: HAST 6000X Bond Strength: Wire Pull (>3.00 grams) Bond Shear (>8.00 grams)	JESD22-A110		231		Parts had been pre-conditioned at 260°C
	Stress Condition: +110°C/85%RH, 528 hrs. Bias Volt: PS1:1.32 Volts, PS3:3.63 Volts System: HAST 6000X Electrical Test: +25°C and 85°C System: LTX_D1X Bond Strength: Wire Pull (>3.00 grams) Bond Shear (>8.00 grams)		45 (0)	0/45	Pass	3 Wire pull & bond shear after HAST
			231(0)	0/231	Pass	
			45 (0)	0/45	Pass	4 Wire pull & bond shear after HAST

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
UNBIASED-HAST	Stress Condition: +110°C/85%RH, 264 hrs. System: HAST 6000X	JESD22- A118		231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C System: LTX_D1X		231(0)	0/231	Pass	77 units / lot
High Temperature Storage Life	Stress Condition: Bake 150°C, 500 hrs System: CHINEE	JESD22- A103		135		45 units / lot
	Electrical Test: +25°C and 85°C System: LTX_D1X		135(0)	0/135	Pass	
	Stress Condition: Bake 150°C, 1000 hrs System: CHINEE			135		
	Electrical Test: +25°C and 85°C System: LTX_D1X		135(0)	0/135	Pass	

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Bond Strength Data Assembly	Wire Pull (> 3.00 grams)	Mil. Std. 883-2011	30 (0) Wires	0/30	Pass	
	Bond Shear (>8.00 grams)	CDF-AEC- Q100-001	30 (0) Bonds	0/30	Pass	



QUALIFICATION REPORT SUMMARY

RELIABILITY LABORATORY

PCN #: DSNO-22ZCDA626

Date:
June 22, 2026

Qualification of MTAI as an additional assembly site for LAN7431/YXX, LAN7431-I/YXX, LAN7431T/YXX, LAN7431T-I/YXX, LAN7431T-V/YXX and LAN7431-V/YXX catalog part numbers (CPN) available in 72L VQFN (10x10x0.9mm) package. This is a Q006 grade 2 qualification and qualification by similarity (QBS).



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PACKAGE QUALIFICATION REPORT

Purpose	Qualification of MTAI as an additional assembly site for LAN7431/YXX, LAN7431-I/YXX, LAN7431T/YXX, LAN7431T-I/YXX, LAN7431T-V/YXX and LAN7431-V/YXX catalog part numbers (CPN) available in 72L VQFN (10x10x0.9mm) package. This is a Q006 grade 2 qualification and qualification by similarity (QBS).
CN	E000267042
QUAL ID	R2500433 Rev. A
MP CODE	STT029YXXVA2
Part No.	USB24915P-V/YXXVAO
Bonding No.	BD-002437 Rev. 01
CCB No.	7525 (Qual Date: July 22, 2025) and 8370
<u>Package</u>	
Type	72L VQFN
Package size	10 x 10mm
<u>Lead Frame</u>	
Paddle size	319 x 319 mils
Material	A194
Surface	Ag Ring Plated
Process	Etched
Lead Lock	No
Part Number	10107201
Treatment	Roughened
<u>Material</u>	
Epoxy	QMI519
Wire	CuPdAu
Mold Compound	G700LTD
Plating Composition	Matte Sn



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PACKAGE QUALIFICATION REPORT

Manufacturing Information

Assembly Lot No.	Wafer Lot No.	Date Code
MTAI255200897.000	TC14924427876.200	25131HV
MTAI255201129.000	TC14924427876.200	251324T
MTAI255201132.000	TC14924427876.200	251324W

Result

☒ Pass ☐ Fail ☐ _____

72L VQFN (10x10mm) assembled by MTAI pass reliability test per QCI-39000. This package was qualified the Moisture/Reflow Sensitivity Classification Level 3 at 260°C reflow temperature per IPC/JEDEC J-STD-020E standard.

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Temp Cycle	Stress Condition: -55°C to +125°C, 1000 Cycles System : TABAI ESPEC TSA-70H Electrical Test: + 25°C and 110°C System: LTX_D1X	JESD22-A104	231(0)	231 0/231	Pass	Parts had been pre-conditioned at 260°C
	Stress Condition: -55°C to +125°C, 2000 Cycles System: TABAI ESPEC TSA-70H Electrical Test: + 25°C and 110°C System: LTX_D1X		231(0)	231 0/231	Pass	
HAST	Stress Condition: +110°C/85%RH, 264 hrs. Bias Volt: VDD33=3.63 Volts System: HAST 6000X	JESD22-A110		231		Parts had been pre-conditioned at 260°C
	Electrical Test: + 25°C and 110°C System: LTX_D1X		231(0)	0/231	Pass	77 units / lot
	Stress Condition: +110°C/85%RH, 528 hrs. Bias Volt: VDD33=3.63 Volts System: HAST 6000X			231		
	Electrical Test: + 25°C and 110°C System: LTX_D1X		231(0)	0/231	Pass	

PACKAGE QUALIFIATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
UNBIASED-HAST	Stress Condition: +110°C/85%RH, 264 hrs. System: HAST 6000X	JESD22-A118		231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C System: LTX_D1X		231(0)	0/231	Pass	77 units / lot
High Temperature Storage Life	Stress Condition: Bake 150°C, 500 hrs System: CHINEE	JESD22-A103		135		45 units / lot
	Electrical Test: +25°C and 110°C System: LTX_D1X		135(0)	0/135	Pass	
	Stress Condition: Bake 150°C, 1000 hrs System: CHINEE			135		
Solderability Temp 245°C	Electrical Test: +25°C and 110°C System: LTX_D1X	J-STD-002	135(0)	0/135	Pass	
	Steam Aging: Temp 93°C,8Hrs System: SAS-3000 Solder Dipping: Solder Temp.245°C Solder material: Pb Free Sn 95.5Ag3.9Cu0.6 System: ERS A RA 2200D Visual Inspection: External Visual Inspection			22		
			22	22		
			22(0)	0/22	Pass	

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Physical Dimensions	Physical Dimension, 10 units from 1 lot	JESD22- B100/B108	30(0) Units	0/30	Pass	
Bond Strength Data Assembly	Wire Pull (> 3.00 grams)	Mil. Std. 883-2011	30 (0) Wires	0/30	Pass	
	Bond Shear (>8.00 grams)	CDF-AEC- Q100-001	30 (0) Bonds	0/30	Pass	